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(54) Title: AUXILIARY PLASMA SOURCE FOR ROBUST IGNITION AND RESTRIKES IN A PLASMA CHAMBER

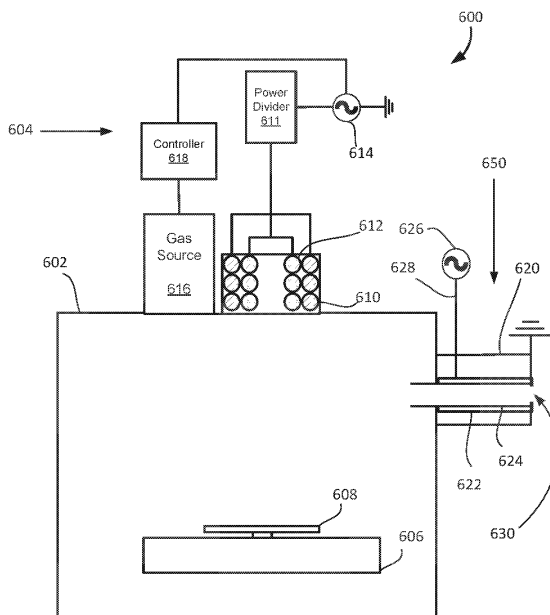


FIG. 6

(57) Abstract: A semiconductor processing system may include a semiconductor processing chamber configured to execute a recipe on a semiconductor wafer. The system may include a first plasma source to provide plasma to the semiconductor processing chamber and to be duty cycled during an execution of the recipe. The system may also include a second plasma source configured to maintain the plasma in the semiconductor processing chamber while the first plasma source is duty cycled.

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